

AMENDMENTS TO THE CLAIMS (AS ON AMENDED SHEET ANNEXED TO IPER)

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (original) Flame retardant polyamide compound comprising a polyamide polymer having a weight-average molecular weight of at least 10.000 g/mol, a halogen-free flame retardant and a polyamide oligomer having a weight-average molecular weight of at most 7500, and wherein the polyamide oligomer is a melt-processable semi-crystalline or amorphous polyamide, characterized in that the halogen-free flame retardant is a halogen-free phosphorous containing flame retardant
2. (original) Compound according to claim 1, wherein the polyamide oligomer is a polyamide with a melting temperature of at least 260°C.
3. (currently amended) Compound according to claim 1 ~~or 2~~, wherein the polyamide oligomer is present in an amount of 0.1-30 weight %, relative to the total weight of polyamide.
4. (currently amended) Compound according to ~~any of claims 1-3~~ claim 1, wherein the halogen-free phosphorous containing flame retardant is a melamine based phosphorous compound.
5. (currently amended) Compound according to ~~any of claims 1-4~~ claim 1, wherein phosphorous containing flame retardant is present in an amount between 1 and 100 parts by weight, relative to a total amount of polyamide of 100 parts by weight.
6. (currently amended) Process for preparing a compound according to ~~any of claims 1-5~~ claim 1 comprising melt-mixing of a polyamide composition comprising a polyamide polymer having a weight-average molecular weight of at least 10.000 g/mol, a polyamide oligomer having a weight-average molecular weight of at most 7500, and a halogen-free phosphorous containing flame retardant.
7. (original) Process according to claim 6, wherein the polyamide polymer is a polyamide with a melting temperature of at least 260°C.

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8. (currently amended) Process according to ~~any of claims 6-7~~ claim 6, wherein the polyamide oligomer has a melting temperature of at most 20°C above the melting temperature of the polyamide polymer.

9. (currently amended) Process according to ~~any of claims 1-5~~ claim 1, wherein the polyamide compound comprises a reinforcing component.

10. (currently amended) Use of a polyamide compound according to ~~any of claims 1-6~~ claim 1 for the preparation of a molded part.

11. (currently amended) Molded part obtainable by melt-processing of a polyamide compound according to ~~any of claims 1-6~~ claim 1.